

MODEL: HSB02-101007 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- small footprint
- aluminum alloy
- black anodized finish



MODEL

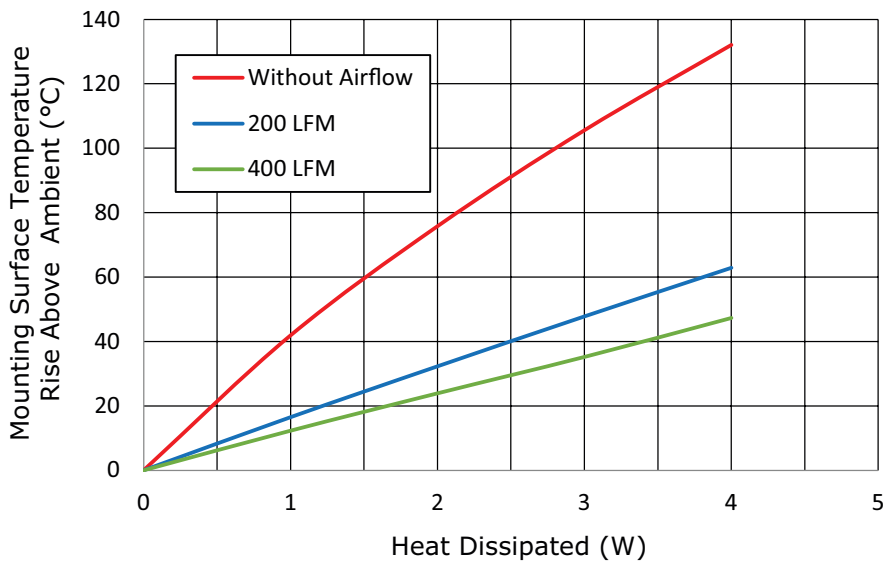
HSB02-101007	thermal resistance ¹				power dissipation ¹
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	@ 75°C ΔT, nat conv [W]
	37.90	41.9	16.50	12.30	1.98

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	41.9	16.5	12.3
2	75.8	32.3	23.9
3	105.6	47.8	35.2
4	132.1	62.9	47.3

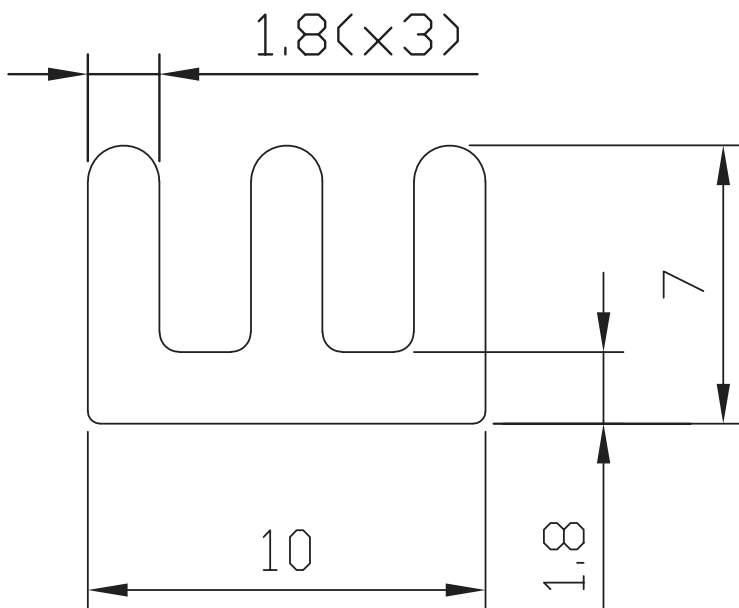
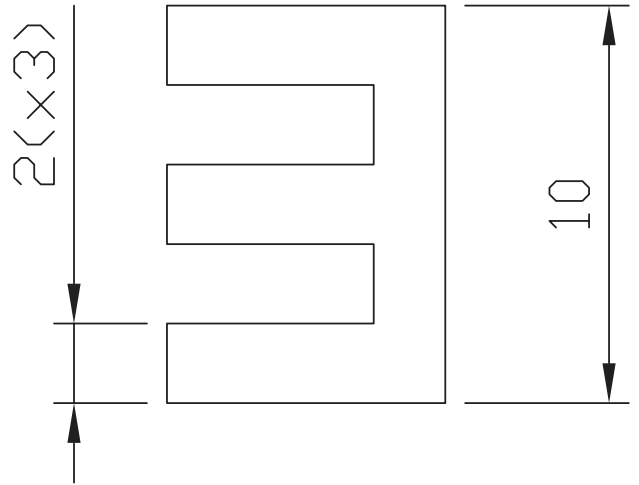
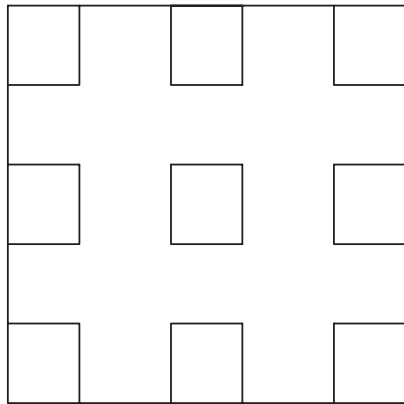
T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ± 0.38 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	1.2 g



REVISION HISTORY

rev.	description	date
1.0	initial release	06/24/2021
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.



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